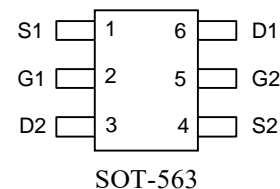
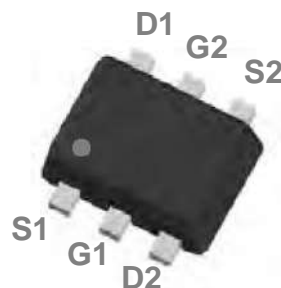


Complementary High Density Trench MOSFET

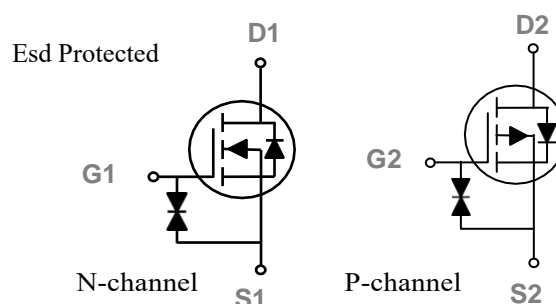
PRODUCT SUMMARY (N-Channel)

V _{DSS}	I _D	R _{DS(on)} (mΩ) Max
20V	0.8A	500@ V _{GS} = 4.5V
	0.6A	800@ V _{GS} = 2.5V



PRODUCT SUMMARY (P-Channel)

V _{DSS}	I _D	R _{DS(on)} (mΩ) Max
-20V	-0.8A	600@ V _{GS} = -4.5V
	-0.6A	800@ V _{GS} = -2.5V



ABSOLUTE MAXIMUM RATINGS (T_A = 25 °C unless otherwise noted)

Parameter	Symbol	N-Channel	P-Channel	Unit
Drain-Source Voltage	V _{DS}	20	-20	V
Gate-Source Voltage	V _{GS}	± 8	± 8	V
Drain Current-Continuous ^a @ T _A = 25 °C -Pulse ^b	I _D	0.8	-0.8	A
	I _{DM}	3	-3	A
Drain-Source Diode Forward Current ^a	I _S	1	-1	A
Maximum Power Dissipation ^a	P _D	0.56		W
		0.33		
Operating Junction and Storage Temperature Range	T _J , T _{STG}	- 55 to 150		°C

THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Ambient ^a	R _{thJA}	250	°C/W
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Note :

a. Surface Mounted on FR4 Board , t ≤ 5sec .

b. Pulse width limited by maximum junction temperature.

ELECTRICAL CHARACTERISTICS (T_A = 25 °C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} = 0V , I _D = 250uA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 20V , V _{GS} = 0V			1	uA
Gate-Body Leakage	I _{GSS}	V _{GS} = ±8V , V _{DS} = 0V			±10	uA
ON CHARACTERISTICS^b						
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250uA	0.5	0.7	1	V
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 4.5V , I _D = 0.8A		300	500	m-ohm
		V _{GS} = 2.5V , I _D = 0.6A		600	800	
Forward Transconductance	g _{fs}	V _{DS} = 5V , I _D = 0.3A		3		S
DRAIN-SOURCE DIODE CHARACTERISTICS^b						
Diode Forward Voltage	V _{SD}	V _{GS} = 0V , I _S = 0.3A		0.7	1.2	V
DYNAMIC CHARACTERISTICS^c						
Input Capacitance	C _{ISS}	V _{DS} = 6V , V _{GS} = 0Vf = 1.0MHz		42		pF
Output Capacitance	C _{OSS}			23		pF
Reverse Transfer Capacitance	C _{RSS}			19		pF
SWITCHING CHARACTERISTICS^c						
Turn-On Delay Time	t _{D(ON)}	V _{DD} = 6V , I _D = 0.3A V _{GEN} = 4.5V		5	9	ns
Rise Time	t _r			15	42	ns
Turn-Off Delay Time	t _{D(OFF)}	R _L = 6 ohm R _{GEN} = 6 ohm		25	28	ns
Fall Time	t _f			7.6		ns
Total Gate Charge	Q _g	V _{DS} = 6V I _D = 0.3A V _{GS} = 4.5V		3.4		nC
Gate-Source Charge	Q _{gs}			2.5		nC
Gate-Drain Charge	Q _{gd}			1.7		nC

Note

b. Pulse Test Pulse width ≤ 300us , Duty Cycle ≤ 2% .

c. Guaranteed by design , not subject to production testing .

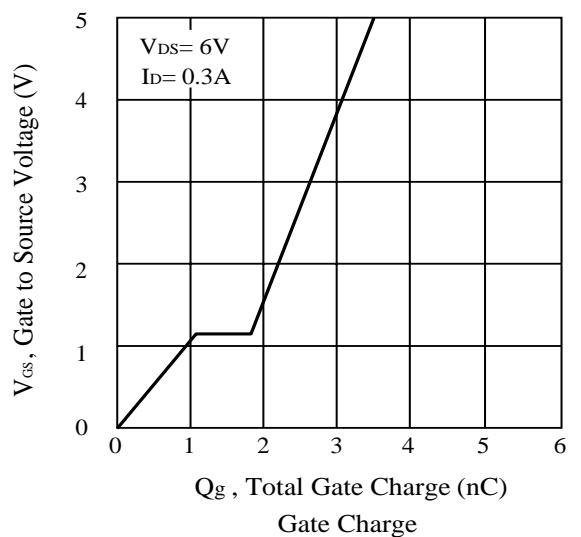
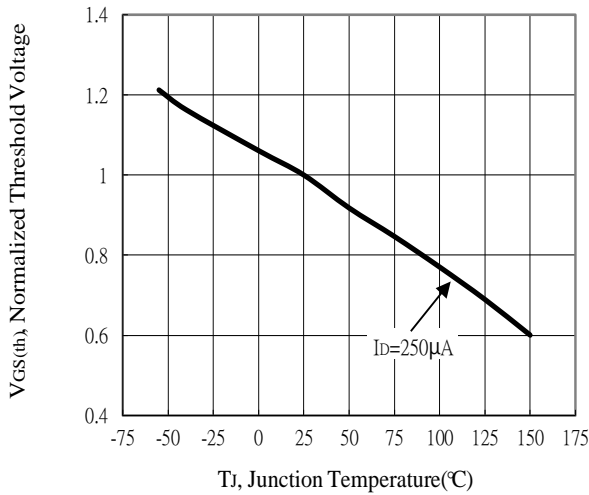
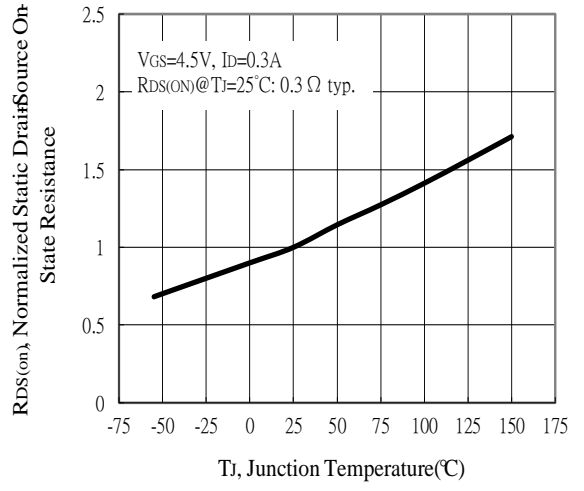
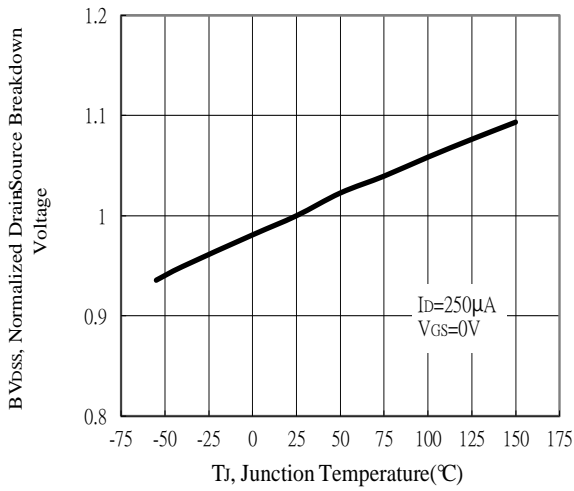
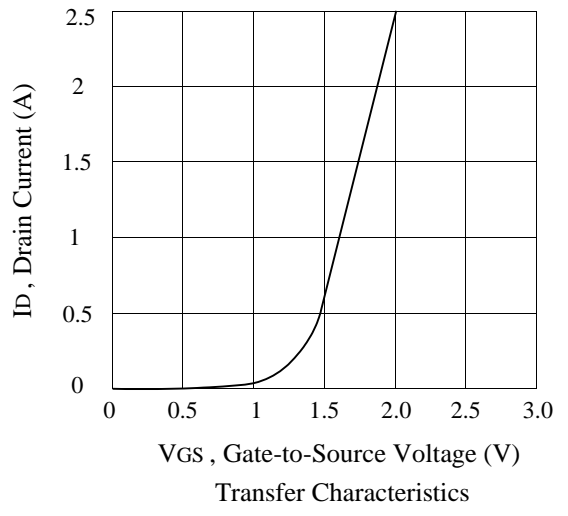
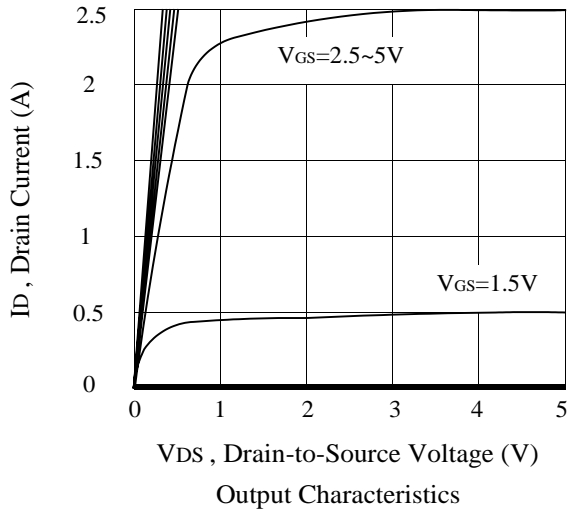
ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

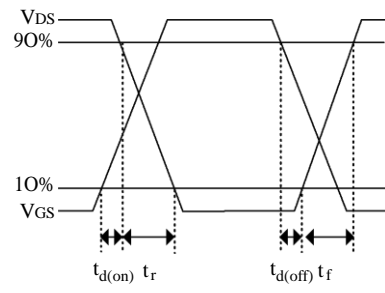
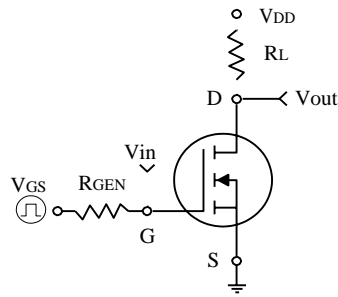
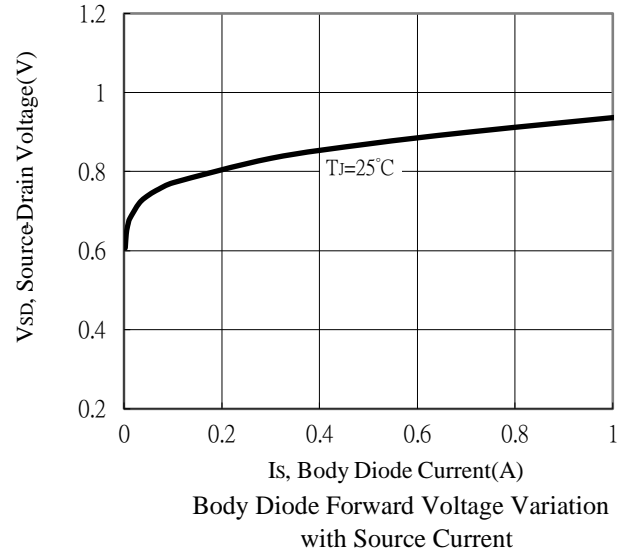
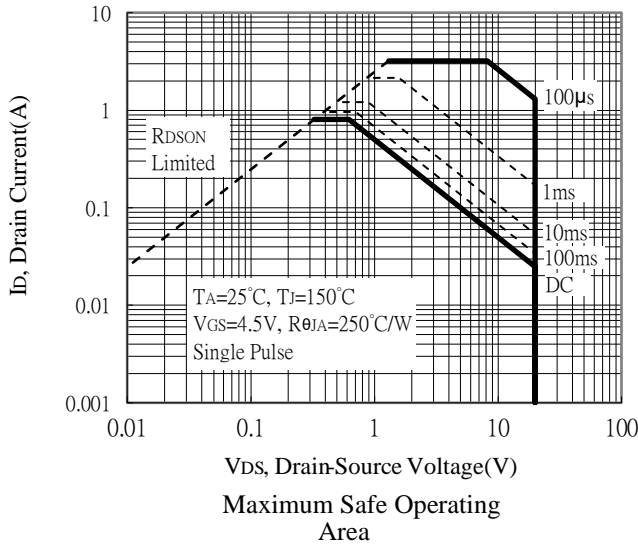
Parameter	Symbol	Condition	Min	Typ ^c	Max	Unit
OFF CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 250\mu A$	-20			V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$			1	μA
Gate-Body Leakage	I_{GSS}	$V_{GS} = \pm 8V, V_{DS} = 0V$			± 10	μA
ON CHARACTERISTICS^b						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	-0.5	-0.7	-1	V
Drain-Source On-State Resistance	$R_{DS(on)}$	$V_{GS} = -4.5V, I_D = -0.8A$		600	800	m-ohm
		$V_{GS} = -2.5V, I_D = -0.6A$		800	1000	
Forward Transconductance	g_{fs}	$V_{DS} = -5V, I_D = -0.5A$		10.7		S
DRAIN-SOURCE DIODE CHARACTERISTICS^b						
Diode Forward Voltage	V_{SD}	$V_{GS} = 0V, I_S = -1.7A$		-0.7	-1.2	V
DYNAMIC CHARACTERISTICS^c						
Input Capacitance	C_{ISS}	$V_{DS} = -6V, V_{GS} = 0V, f = 1.0MHz$		50.7		pF
Output Capacitance	C_{OSS}			12.8		pF
Reverse Transfer Capacitance	C_{RSS}			7.1		pF
SWITCHING CHARACTERISTICS^c						
Turn-On Delay Time	$t_{D(ON)}$	$V_{DD} = -6V, I_D = -0.8A$		6	9	ns
Rise Time	t_r	$V_{GEN} = 4.5V$		12	38	ns
Turn-Off Delay Time	$t_{D(OFF)}$	$R_L = 6\text{ ohm}$		27	36	ns
Fall Time	t_f	$R_{GEN} = 6\text{ ohm}$		6.8		ns
Total Gate Charge	Q_g	$V_{DS} = -6V$		18		nC
Gate-Source Charge	Q_{gs}	$I_D = -0.8A$		4.2		nC
Gate-Drain Charge	Q_{gd}	$V_{GS} = -4.5V$		2.8		nC

Note

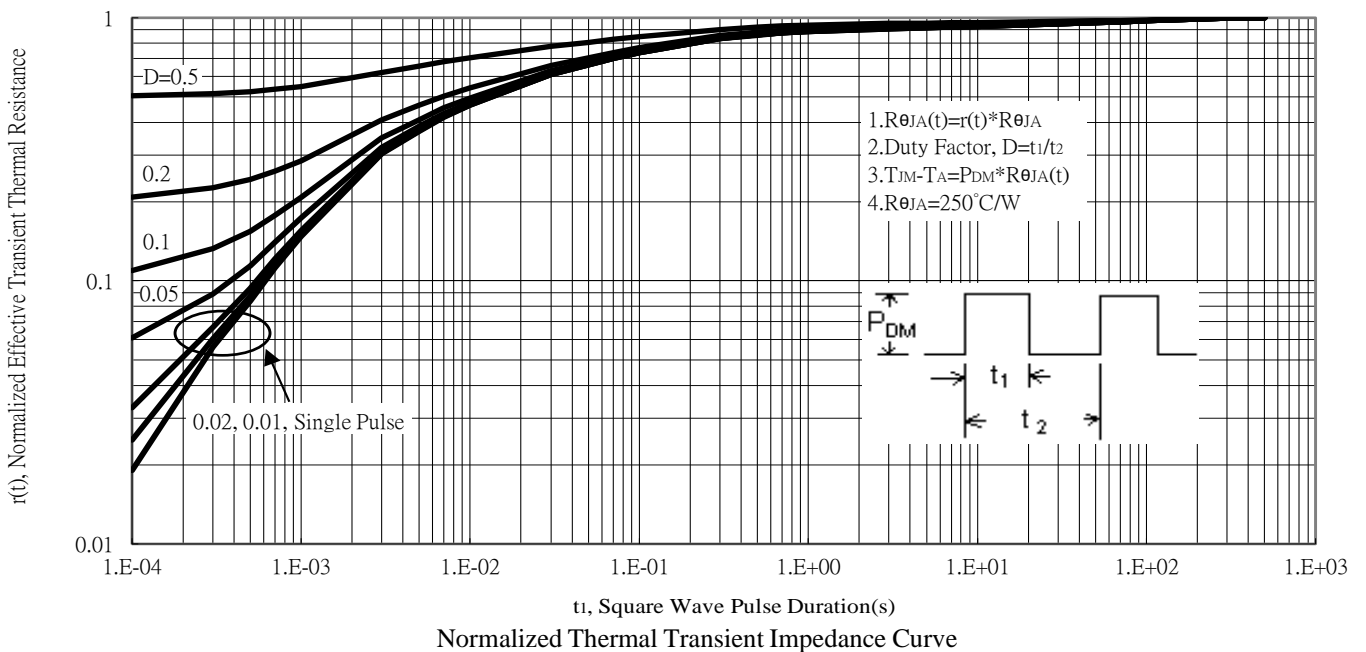
b. Pulse Test Pulse width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.

c. Guaranteed by design, not subject to production testing.

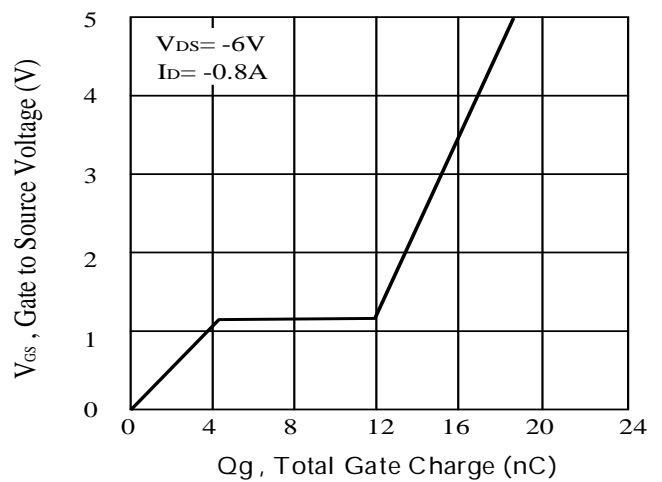
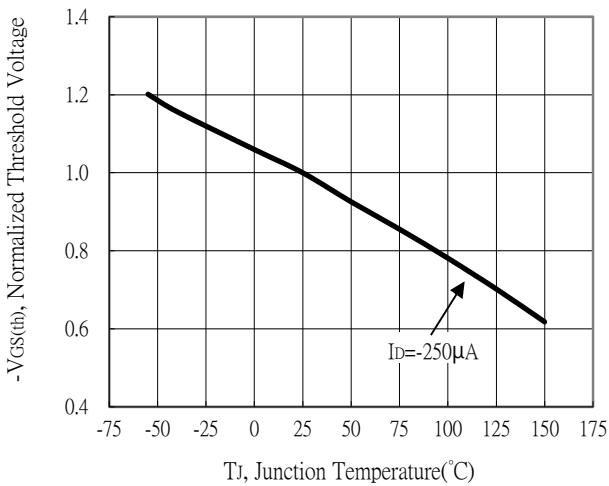
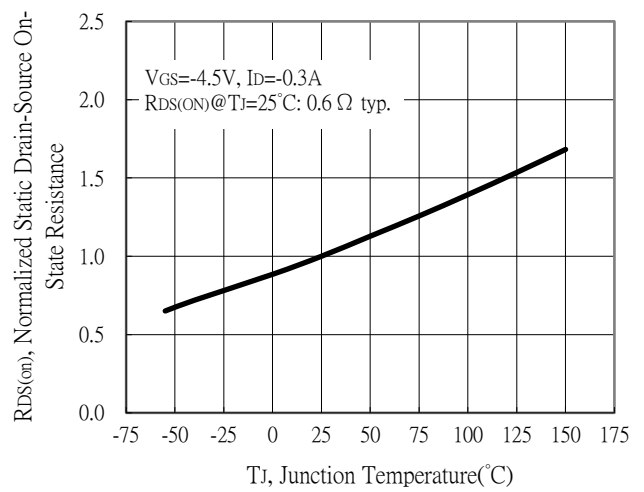
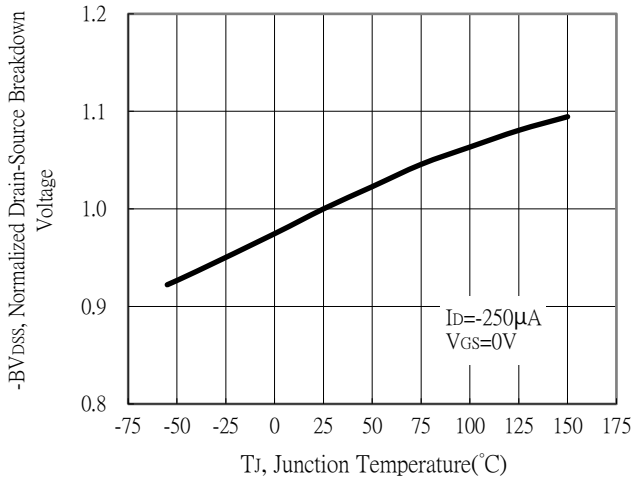
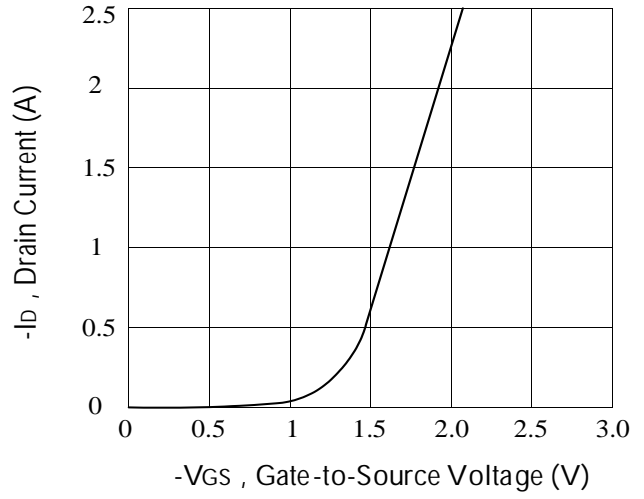
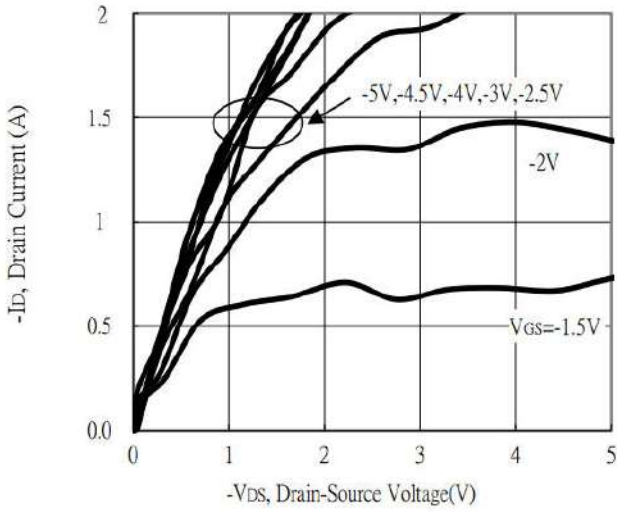


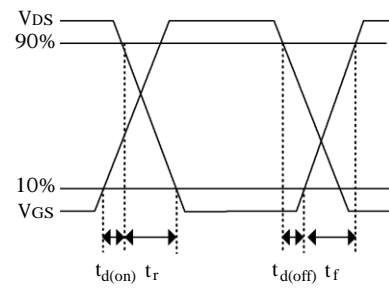
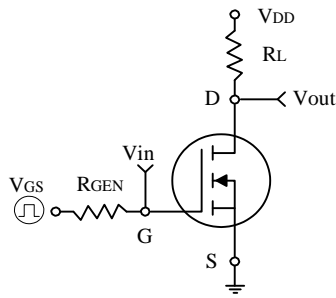
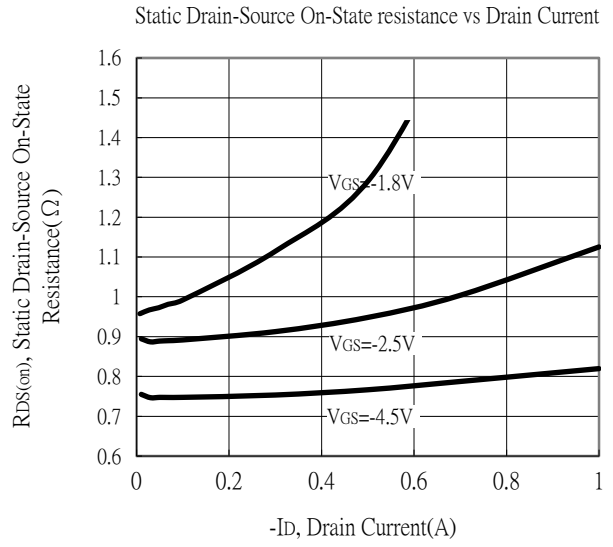
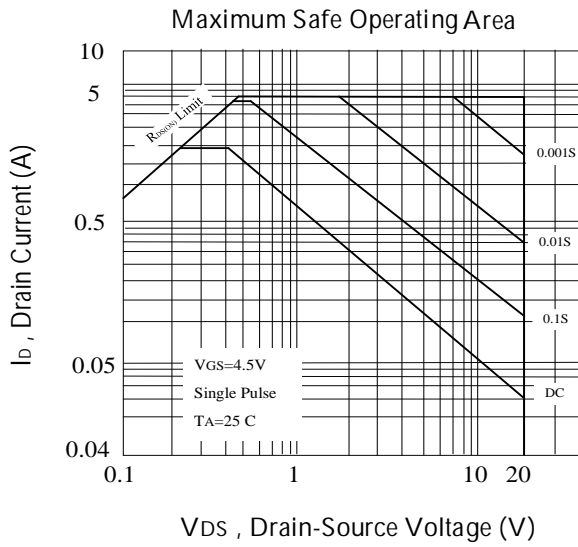


Switching Test Circuit and Switching Waveforms



Typical Output Characteristics





Switching Test Circuit and Switching Waveforms

